

ABSTRACT OF THE DISCLOSURE

A problem arose in that when gas holes defined in
a gas-introducing plate lying within a plasma etching
apparatus reached more than a given size, plasma entered
5 from an etching-processing chamber to the backside
(cooling plate side) of a gas-introducing plate through
the gas holes.

In order to solve such a problem, there is
provided an upper electrode which comprises a cooling
10 plate having a plurality of gas supply holes for
supplying gas, a gas-introducing plate having gas holes
for introducing the gas into a semiconductor wafer
uniformly, a jig for fixing the gas-introducing plate to
the cooling plate, and a sensor for detecting plasma.

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